

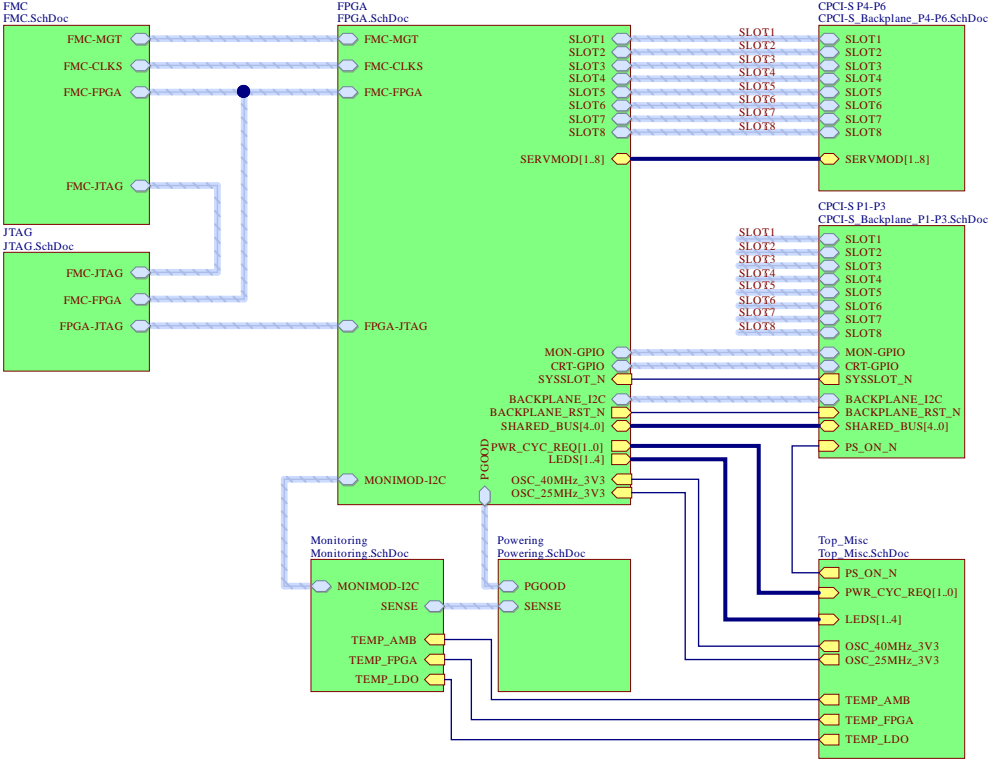
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Source location: <https://www.ohwr.org/project/diot-sb-ig1>

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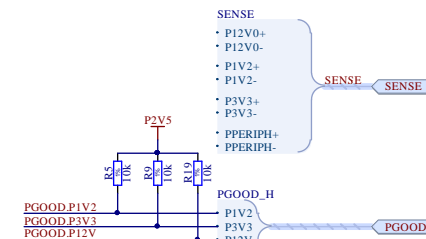
| | | | |
|-------------------|--|------------|------------------------|
| Project/Equipment | | DI/OT | |
| Document | | Designer | C. Gentsos |
| | | Drawn by | C. Gentsos |
| | | Check by | * |
| | | Last Mod. | C. Gentsos |
| | | File | DIOT-sb-ig1_top.SchDoc |
| | | Print Date | 09/10/2020 11:02:41 |
| | | Sheet | 1 of 17 |
| | | Size | A3 |
| | | Rev | * |

DI/OT Rad-tol System Board
Top Level

European Organization for Nuclear Research
CH-1211 Genève 23 - Switzerland

EDA-XXXXX-VX-X

Diagram illustrating the placement of test points (TP1 to TP13) and power pins (P12V0 to PGOOD.P12V3) on the top layer of a PCB. The test points are located near the power pins. A callout box indicates: "Place Test Points on top layer".

[illegible]

The diagram illustrates the connection between a 10W DC/DC Converter Module (PCBM1) and a FEASTMP module (J11). The module includes pins for VOUT (1-4), GND (5-8), VIN (9-10), EN (11), and PGOOD (12). The output P12V0 is connected to a 4.7k resistor (R4) and a 100mF capacitor (C2). The PGOOD pin is connected to a 1k resistor (R6) and a 100mF capacitor (C3). The output is also connected to a sense resistor (R7) and a sense capacitor (C3). The output voltage is labeled P12V2 and the sense voltage is labeled SENSE P12V2.

A For a current of 2A, the 100mOhm will dissipate 0.4W (shared between the two 0.25W Rs) and drop 200mV, leaving enough headroom for the dropout voltage. On the other hand, the lower dropout margin will force VCONTROL to draw more current. It might be better to remove those but that's not clear from the datasheet plots, we need to experiment.

VCONTROL powered by +12V to allow low dropout operation

P(worst case) = $(12 \times 1.05 - 2.5 \times 0.95) \times 0.08 + (3.3 \times 1.05 - 0.2 - 2.5 \times 0.95) \times 2 = 2.6W$
T(worst case) = P^*0

IC2 LT3083EQ#PBF

P12V0

5V / 50uA = 50kOhm

[illegible]

1.8V / 50uA = 36kOhm

$(18k + 5.7k) * 1.188V / 5.7k = 4.93V$

Vh for EN is 2.1V, we can use the 3V3 PG00D directly

Diagram of the 3.3V voltage regulator circuit using the IC27 (TPS7A49) LDO. The input is P5V0_SBY, connected to the IN pin. The output is P3V3_SBY, connected to the OUT pin. The EN pin is connected to the input. The NR/SS pin is connected to the input. The FB pin is connected to the output. The NC pin is connected to ground. The EP pin is connected to ground. The GND pin is connected to ground. The input capacitor C214 is 100nF. The output capacitor C221 is 100nF. The feedback resistor R403 is 10k. The output resistor R404 is 4k. A callout box shows the calculation: $(10k + 5.7k) \cdot 1.188V / 5.7k = 3.27V$.

The schematic diagram shows two identical power supply stages. Each stage consists of a series combination of a 220R resistor, a 100mH inductor, and a 22uF capacitor, followed by a shunt 100uF capacitor to ground. The input and output voltages are P3V3 and P3V3_A for the first stage, and P5V0 and P5V0_A for the second stage. The components are labeled with their values and identifiers: C29, C30, C31, C63, C64, C65, C95, C96, C97, C28, C27, C26, C25, C24, C23, C22, C21, C20, C19, C18, C17, C16, C15, C14, C13, C12, C11, C10, C9, C8, C7, C6, C5, C4, C3, C2, C1, C0, C-1, C-2, C-3, C-4, C-5, C-6, C-7, C-8, C-9, C-10, C-11, C-12, C-13, C-14, C-15, C-16, C-17, C-18, C-19, C-20, C-21, C-22, C-23, C-24, C-25, C-26, C-27, C-28, C-29, C-30, C-31, C-32, C-33, C-34, C-35, C-36, C-37, C-38, C-39, C-40, C-41, C-42, C-43, C-44, C-45, C-46, C-47, C-48, C-49, C-50, C-51, C-52, C-53, C-54, C-55, C-56, C-57, C-58, C-59, C-60, C-61, C-62, C-63, C-64, C-65, C-66, C-67, C-68, C-69, C-70, C-71, C-72, C-73, C-74, C-75, C-76, C-77, C-78, C-79, C-80, C-81, C-82, C-83, C-84, C-85, C-86, C-87, C-88, C-89, C-90, C-91, C-92, C-93, C-94, C-95, C-96, C-97, C-98, C-99, C-100, C-101, C-102, C-103, C-104, C-105, C-106, C-107, C-108, C-109, C-110, C-111, C-112, C-113, C-114, C-115, C-116, C-117, C-118, C-119, C-120, C-121, C-122, C-123, C-124, C-125, C-126, C-127, C-128, C-129, C-130, C-131, C-132, C-133, C-134, C-135, C-136, C-137, C-138, C-139, C-140, C-141, C-142, C-143, C-144, C-145, C-146, C-147, C-148, C-149, C-150, C-151, C-152, C-153, C-154, C-155, C-156, C-157, C-158, C-159, C-160, C-161, C-162, C-163, C-164, C-165, C-166, C-167, C-168, C-169, C-170, C-171, C-172, C-173, C-174, C-175, C-176, C-177, C-178, C-179, C-180, C-181, C-182, C-183, C-184, C-185, C-186, C-187, C-188, C-189, C-190, C-191, C-192, C-193, C-194, C-195, C-196, C-197, C-198, C-199, C-200, C-201, C-202, C-203, C-204, C-205, C-206, C-207, C-208, C-209, C-210, C-211, C-212, C-213, C-214, C-215, C-216, C-217, C-218, C-219, C-220, C-221, C-222, C-223, C-224, C-225, C-226, C-227, C-228, C-229, C-230, C-231, C-232, C-233, C-234, C-235, C-236, C-237, C-238, C-239, C-240, C-241, C-242, C-243, C-244, C-245, C-246, C-247, C-248, C-249, C-250, C-251, C-252, C-253, C-254, C-255, C-256, C-257, C-258, C-259, C-260, C-261, C-262, C-263, C-264, C-265, C-266, C-267, C-268, C-269, C-270, C-271, C-272, C-273, C-274, C-275, C-276, C-277, C-278, C-279, C-280, C-281, C-282, C-283, C-284, C-285, C-286, C-287, C-288, C-289, C-290, C-291, C-292, C-293, C-294, C-295, C-296, C-297, C-298, C-299, C-300, C-301, C-302, C-303, C-304, C-305, C-306, C-307, C-308, C-309, C-310, C-311, C-312, C-313, C-314, C-315, C-316, C-317, C-318, C-319, C-320, C-321, C-322, C-323, C-324, C-325, C-326, C-327, C-328, C-329, C-330, C-331, C-332, C-333, C-334, C-335, C-336, C-337, C-338, C-339, C-340, C-341, C-342, C-343, C-344, C-345, C-346, C-347, C-348, C-349, C-350, C-351, C-352, C-353, C-354, C-355, C-356, C-357, C-358, C-359, C-360, C-361, C-362, C-363, C-364, C-365, C-366, C-367, C-368, C-369, C-370, C-371, C-372, C-373, C-374, C-375, C-376, C-377, C-378, C-379, C-380, C-381, C-382, C-383, C-384, C-385, C-386, C-387, C-388, C-389, C-390, C-391, C-392, C-393, C-394, C-395, C-396, C-397, C-398, C-399, C-400, C-401, C-402, C-403, C-404, C-405, C-406, C-407, C-408, C-409, C-410, C-411, C-412, C-413, C-414, C-415, C-416, C-417, C-418, C-419, C-420, C-421, C-422, C-423, C-424, C-425, C-426, C-427, C-428, C-429, C-430, C-431, C-432, C-433, C-434, C-435, C-436, C-437, C-438, C-439, C-440, C-441, C-442, C-443, C-444, C-445, C-446, C-447, C-448, C-449, C-450, C-451, C-452, C-453, C-454, C-455, C-456, C-457, C-458, C-459, C-460, C-461, C-462, C-463, C-464, C-465, C-466, C-467, C-468, C-469, C-470, C-471, C-472, C-473, C-474, C-475, C-476, C-477, C-478, C-479, C-480, C-481, C-482, C-483, C-484, C-485, C-486, C-487, C-488, C-489, C-490, C-491, C-492, C-493, C-494, C-495, C-496, C-497, C-498, C-499, C-500, C-501, C-502, C-503, C-504, C-505, C-506, C-507, C-508, C-509, C-510, C-511, C-512, C-513, C-514, C-515, C-516, C-517, C-518, C-519, C-520, C-521, C-522, C-523, C-524, C-525, C-526, C-527, C-528, C-529, C-530, C-531, C-532, C-533, C-534, C-535, C-536, C-537, C-538, C-539, C-540, C-541, C-542, C-543, C-544, C-545, C-546, C-547, C-548, C-549, C-550, C-551, C-552, C-553, C-554, C-555, C-556, C-557, C-558, C-559, C-560, C-561, C-562, C-563, C-564, C-565, C-566, C-567, C-568, C-569, C-570, C-571, C-572, C-573, C-574, C-575, C-576, C-577, C-578, C-579, C-580, C-581, C-582, C-583, C-584, C-585, C-586, C-587, C-588, C-589, C-590, C-591, C-592, C-593, C-594, C-595, C-596, C-597, C-598, C-599, C-600, C-601, C-602, C-603, C-604, C-605, C-606, C-607, C-608, C-609, C-610, C-611, C-612, C-613, C-614, C-615, C-616, C-617, C-618, C-619, C-620, C-621, C-622, C-623, C-624, C-625, C-626, C-627, C-628, C-629, C-630, C-631, C-632, C-633, C-634, C-635, C

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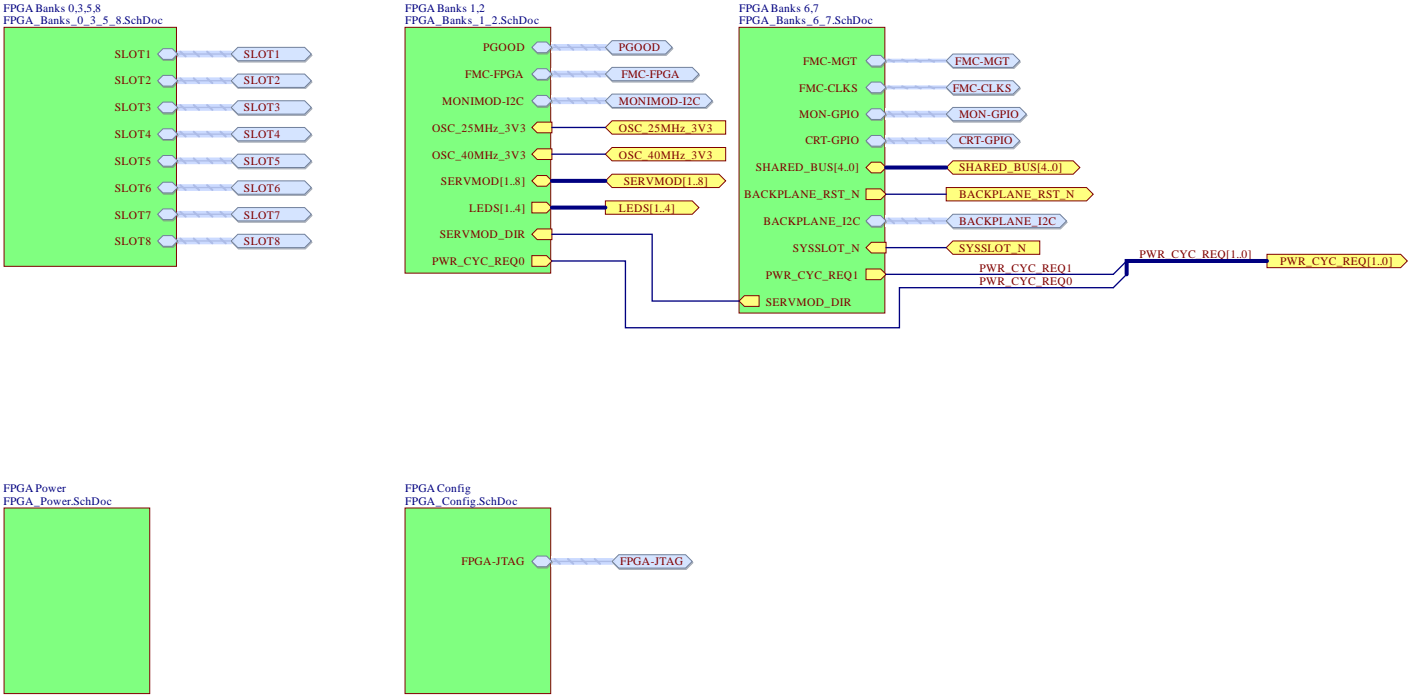
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| | | | |
|-------------------|--|------------|---------------------|
| Project/Equipment | | DI/OT | |
| Document | | Designer | C. Gentsos |
| | | Drawn by | C. Gentsos |
| | | Check by | * |
| | | Last Mod. | C. Gentsos |
| | | File | FPGA.SchDoc |
| | | Print Date | 09/10/2020 11:02:42 |
| | | Sheet | 3 of 17 |
| | | Size | A3 |
| | | Rev | * |

BE/CO

DI/OT Rad-tol System Board

FPGA Top

European Organization for Nuclear Research
CH-1211 Genève 23 - Switzerland

EDA-XXXXX-VX-X

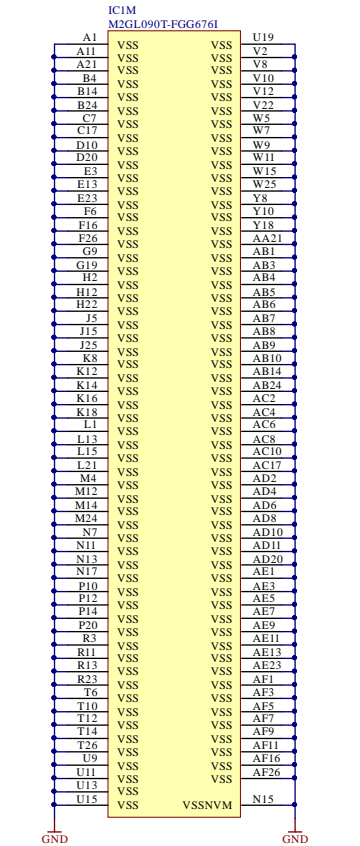
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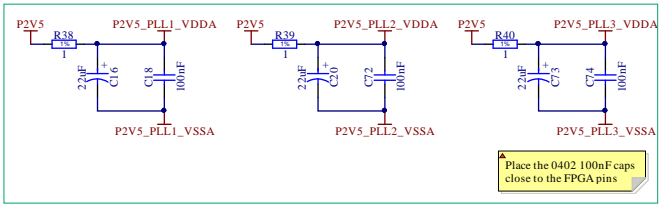
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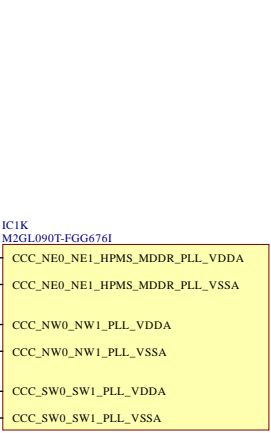
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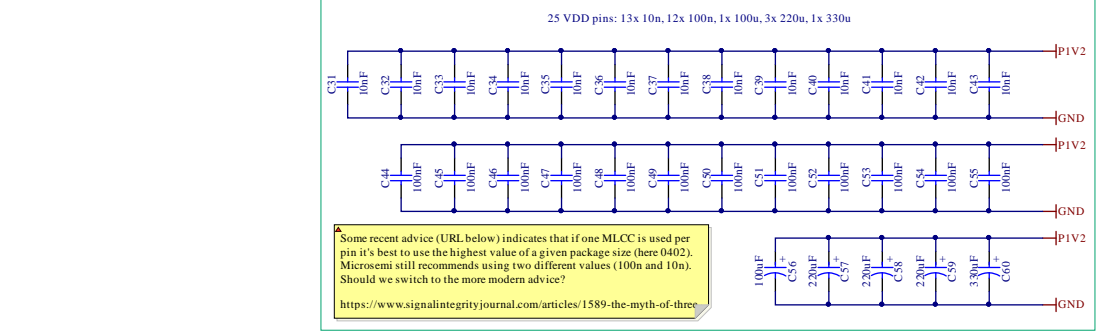
VPPNVM must be shorted to VPP



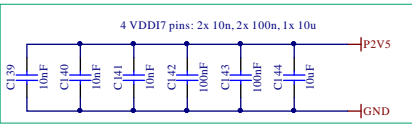
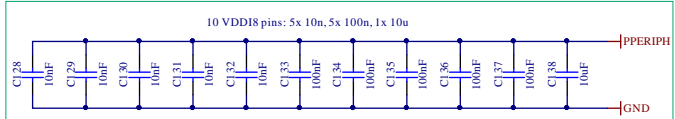
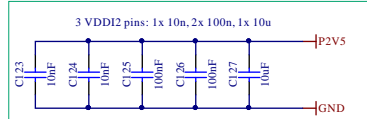
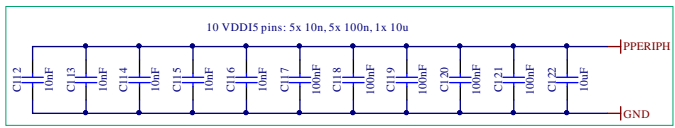
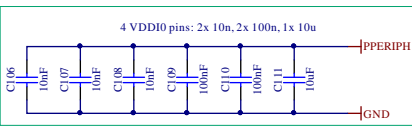
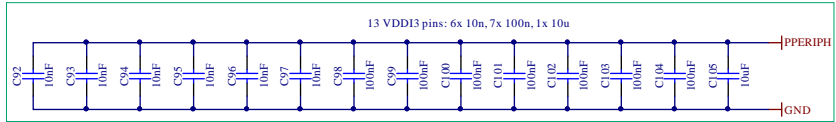
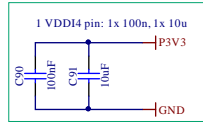
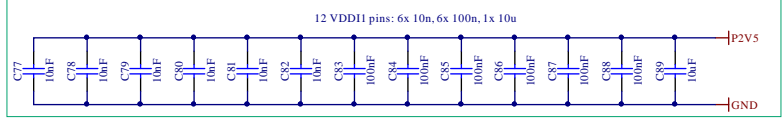
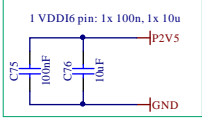
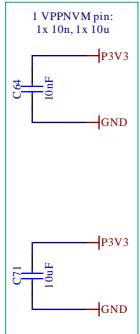
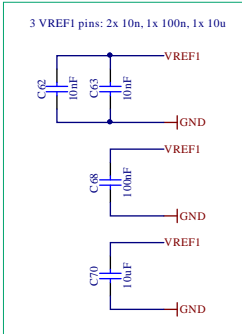
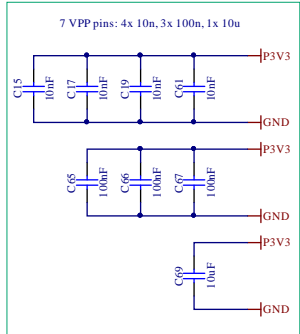
Place the 0402 100nF caps close to the FPGA pins



PLL power, 2.5V or 3.3V? 2.5V will be smoother due to the LDO so better jitter but is any of the two better for radiation?



Some recent advice (URL below) indicates that if one MLCC is used per pin it's best to use the highest value of a given package size (here 0402). Microsemi still recommends using two different values (100n and 10n). Should we switch to the more modern advice? <https://www.signalintegrityjournal.com/articles/1589-the-myth-of-three>



| | |
|-------------------|---------------------|
| Project/Equipment | DI/OT |
| Document | BE/CO |
| Designer | C. Gentsos |
| Drawn by | C. Gentsos |
| Check by | * |
| Last Mod. | C. Gentsos |
| File | FPGA_PowerSchDoc |
| Print Date | 09/10/2020 11:02:43 |
| Sheet | 4 of 17 |
| A3 | * |

DI/OT Rad-tol System Board
FPGA Power
European Organization for Nuclear Research
CH-1211 Genève 23 - Switzerland

EDA-XXXXX-VX-X

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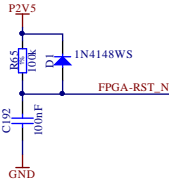
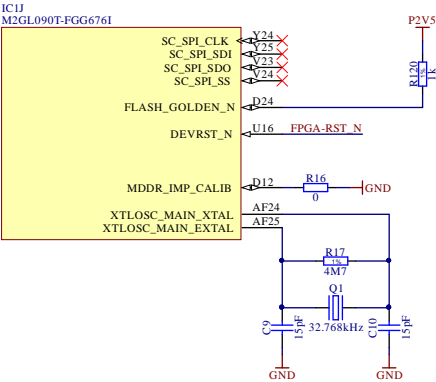
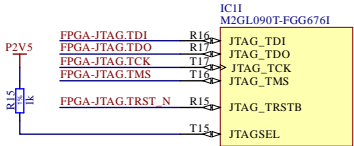
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Parts powered by 2.5V



The JTAG and configuration pins are referred to as Bank 4



| | | | |
|--|--|----------------|---------------------|
| Project/Equipment | | DI/OT | |
| Document | | Designer | C. Gentsos |
| <div>BE/CO</div> <div></div> | | Drawn by | C. Gentsos |
| | | Check by | * |
| | | Last Mod. | C. Gentsos |
| | | File | FPGA_Config.SchDoc |
| | | Print Date | 09/10/2020 11:02:44 |
| <div>European Organization for Nuclear Research</div> <div>CH-1211 Genève 23 - Switzerland</div> | | Sheet | 5 of 17 |
| | | Rev | A3 |
| | | EDA-XXXXX-VX-X | |

Banks powered by 2.5V

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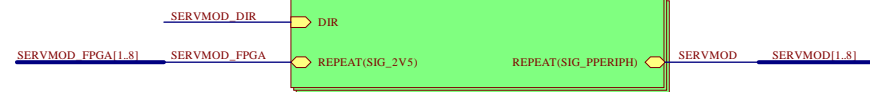
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Careful with pin swapping: the P nets of the differential pairs 0, 1, 17 and 18 are connected to clock-capable pins and can't be swapped with the other I/Os.

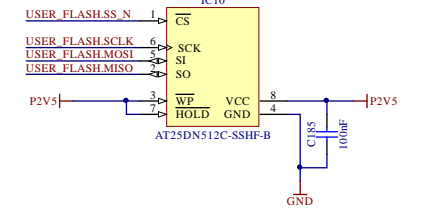
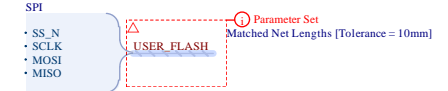
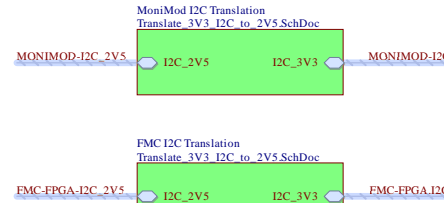
IC1B
M2GL090T-FGG6761

| | | | |
|--------|---|-----|-------------------|
| BANK 1 | DDRIO62NB1/MDDR_ADDR15 | C23 | FMC-FPGA.LA.D_N14 |
| | DDRIO62PB1/MDDR_ADDR14 | C22 | FMC-FPGA.LA.D_P14 |
| | DDRIO63NB1/MDDR_ADDR15 | C23 | FMC-FPGA.LA.D_N15 |
| | DDRIO63PB1/MDDR_ADDR12 | C23 | FMC-FPGA.LA.D_P15 |
| | DDRIO64NB1/MDDR_ADDR11 | C21 | FMC-FPGA.LA.D_N2 |
| | DDRIO64PB1/MDDR_ADDR10 | C20 | FMC-FPGA.LA.D_N3 |
| | DDRIO65NB1/MDDR_ADDR9 | C20 | FMC-FPGA.LA.D_P3 |
| | DDRIO65PB1/MDDR_ADDR8 | C22 | FMC-FPGA.LA.D_N4 |
| | DDRIO66NB1/MDDR_ADDR7 | C22 | FMC-FPGA.LA.D_P4 |
| | DDRIO67NB1/MDDR_ODT | C18 | FMC-FPGA.LA.D_N5 |
| | DDRIO67PB1/MDDR_ADDR6 | C18 | FMC-FPGA.LA.D_P5 |
| | DDRIO68NB1/MDDR_ADDR5 | C21 | FMC-FPGA.LA.D_N6 |
| | DDRIO68PB1/MDDR_ADDR4 | C21 | FMC-FPGA.LA.D_P6 |
| | DDRIO69NB1/MDDR_ADDR3 | C19 | FMC-FPGA.LA.D_N7 |
| | DDRIO69PB1/MDDR_ADDR2 | C19 | FMC-FPGA.LA.D_P7 |
| | DDRIO70NB1/MDDR_ADDR0 | C18 | FMC-FPGA.LA.D_N8 |
| | DDRIO70PB1/MDDR_BA2 | C17 | FMC-FPGA.LA.D_P8 |
| | DDRIO71NB1/MDDR_BA1 | C20 | FMC-FPGA.LA.D_N9 |
| | DDRIO71PB1/MDDR_BA0 | C20 | FMC-FPGA.LA.D_P9 |
| | DDRIO72NB1/MDDR_CLK_N | C20 | FMC-FPGA.LA.D_N10 |
| | DDRIO72PB1/MDDR_CLK_N | C19 | FMC-FPGA.LA.D_P10 |
| | DDRIO73NB1/MDDR_CAS_N | C19 | FMC-FPGA.LA.D_N11 |
| | DDRIO73PB1/MDDR_RESET_N | C18 | FMC-FPGA.LA.D_P11 |
| | DDRIO74NB1/MDDR_CS_N | C17 | FMC-FPGA.LA.D_N12 |
| | DDRIO74PB1/MDDR_CKE | C16 | FMC-FPGA.LA.D_P12 |
| | DDRIO75NB1/MDDR_WE_N | C16 | FMC-FPGA.LA.D_N13 |
| | DDRIO75PB1/MDDR_RAS_N | C16 | FMC-FPGA.LA.D_P13 |
| | DDRIO76NB1/MDDR_DQ15 | C19 | FMC-FPGA.LA.D_N1 |
| | DDRIO76PB1/CCC_NE1_CLK13/MDDR_DQ14 | C18 | FMC-FPGA.LA.D_P1 |
| | DDRIO77NB1/MDDR_DQ13 | C18 | FMC-FPGA.LA.D_N12 |
| | DDRIO77PB1/MDDR_DQ12/GB12/CCC_NE1_CLK12 | C15 | FMC-FPGA.LA.D_P0 |
| | DDRIO78NB1/MDDR_DM_RDQS1 | C16 | FMC-FPGA.LA.D_N16 |
| | DDRIO78PB1/MDDR_TMATCH_0_IN | C16 | FMC-FPGA.LA.D_P16 |
| | DDRIO79NB1/MDDR_DQS1_N | C17 | FMC-FPGA.LA.D_N17 |
| | DDRIO79PB1/MDDR_DQS1/GB8/CCC_NE0_CLK13 | C17 | FMC-FPGA.LA.D_P17 |
| | DDRIO80NB1/MDDR_DQ11 | C16 | FMC-FPGA.LA.D_N18 |
| | DDRIO80PB1/MDDR_DQ10/CCC_NE0_CLK12 | C16 | FMC-FPGA.LA.D_P18 |
| | DDRIO81NB1/MDDR_DQ9 | C16 | FMC-FPGA.LA.D_N19 |
| | DDRIO81PB1/MDDR_DQ8 | C16 | FMC-FPGA.LA.D_P19 |
| | DDRIO82NB1/MDDR_TMATCH_0_OUT | C15 | FMC-FPGA.LA.D_N20 |
| | DDRIO82PB1/MDDR_DQ7 | C15 | FMC-FPGA.LA.D_P20 |
| | DDRIO83NB1/MDDR_DQ6 | C16 | FMC-FPGA.LA.D_N21 |
| | DDRIO83PB1/MDDR_DQ5 | C15 | FMC-FPGA.LA.D_P21 |
| | DDRIO84NB1/MDDR_DQ4 | C14 | FMC-FPGA.LA.D_N22 |
| | DDRIO84PB1/MDDR_DM_RDQS0 | C15 | FMC-FPGA.LA.D_P22 |
| | DDRIO85NB1/MDDR_DQ3 | C15 | FMC-FPGA.LA.D_N23 |
| | DDRIO85PB1/MDDR_DQ2 | C14 | FMC-FPGA.LA.D_P23 |
| | DDRIO86NB1/MDDR_DQ1 | C14 | FMC-FPGA.LA.D_N24 |
| | DDRIO86PB1/MDDR_DQ0 | C15 | FMC-FPGA.LA.D_P24 |
| | DDRIO87NB1/MDDR_DQ0 | C13 | FMC-FPGA.LA.D_N25 |
| | DDRIO87PB1/CCC_NW1_CLK13 | C13 | FMC-FPGA.LA.D_P25 |
| | DDRIO88NB1/MDDR_DQ_ECC0 | C13 | FMC-FPGA.LA.D_N26 |
| | DDRIO88PB1/MDDR_DQ_ECC1 | C13 | FMC-FPGA.LA.D_P26 |
| | DDRIO89NB1/MDDR_DQ_ECC2 | C13 | FMC-FPGA.LA.D_N27 |
| | DDRIO89PB1/MDDR_DQ_ECC3 | C13 | FMC-FPGA.LA.D_P27 |
| | DDRIO90NB1/MDDR_DM_RDQS_ECC | C12 | FMC-FPGA.LA.D_N28 |
| | DDRIO90PB1/MDDR_TMATCH_ECC_IN | C12 | FMC-FPGA.LA.D_P28 |
| | DDRIO91NB1/MDDR_DQS_ECC_N | C12 | FMC-FPGA.LA.D_N29 |
| | DDRIO91PB1/MDDR_DQS_ECC | C12 | FMC-FPGA.LA.D_P29 |
| | DDRIO92NB1/GB4/CCC_NW1_CLK12 | C12 | FMC-FPGA.LA.D_N30 |
| | DDRIO92PB1/GB0/CCC_NW0_CLK13 | C12 | FMC-FPGA.LA.D_P30 |
| | DDRIO93NB1/CCC_NW0_CLK12 | C13 | FMC-FPGA.LA.D_N31 |
| | DDRIO93PB1/MDDR_TMATCH_ECC_OUT | C14 | FMC-FPGA.LA.D_P31 |
| | DDRIO94NB1 | C11 | FMC-FPGA.LA.D_N32 |
| | DDRIO94PB1 | C11 | FMC-FPGA.LA.D_P32 |
| | DDRIO95NB1 | C11 | FMC-FPGA.LA.D_N33 |
| | DDRIO95PB1 | C10 | FMC-FPGA.LA.D_P33 |
| | DDRIO96NB1 | C10 | FMC-FPGA.LA.D_N34 |
| | DDRIO96PB1 | C12 | FMC-FPGA.LA.D_P34 |
| | DDRIO97NB1 | C11 | FMC-FPGA.LA.D_N35 |
| | DDRIO97PB1 | C11 | FMC-FPGA.LA.D_P35 |
| | DDRIO98NB1 | C9 | FMC-FPGA.LA.D_N36 |
| | DDRIO98PB1 | C10 | FMC-FPGA.LA.D_P36 |
| | DDRIO99NB1 | C9 | FMC-FPGA.LA.D_N37 |
| | DDRIO99PB1 | C9 | FMC-FPGA.LA.D_P37 |



IC1C
M2GL090T-FGG6761

| | | | |
|--------|------------------------------|-----|---------------------|
| BANK 2 | MSIO51NB2 | E25 | FMC-FPGA.PRSNT |
| | MSIO51PB2 | E26 | PWR_CYC_REQ0 |
| | MSIO52NB2 | D26 | OSC_25MHz_2V5 |
| | MSIO52PB2/CCC_NE0_CLK11 | D25 | OSC_25MHz_2V5 |
| | MSIO53PB2/CCC_NE1_CLK11 | B26 | OSC_40MHz_2V5 |
| | MSIO54NB2 | E24 | LEDS1 |
| | MSIO54PB2/GB10/VCCC_SE0_CLK1 | E25 | LEDS2 |
| | MSIO55NB2 | E24 | LEDS3 |
| | MSIO55PB2/GB14/VCCC_SE1_CLK1 | E22 | LEDS4 |
| | MSIO56NB2 | G23 | SERVMOD_FPGA1 |
| | MSIO56PB2 | G23 | SERVMOD_FPGA2 |
| | MSIO57NB2 | A24 | SERVMOD_FPGA3 |
| | MSIO57PB2 | A25 | SERVMOD_FPGA4 |
| | MSIO58NB2 | C24 | SERVMOD_FPGA5 |
| | MSIO58PB2 | C25 | SERVMOD_FPGA6 |
| | MSIO59NB2 | D23 | PGOOD_P12V |
| | MSIO60NB2 | E22 | SERVMOD_FPGA7 |
| | MSIO60PB2 | E22 | SERVMOD_FPGA8 |
| | MSIO61NB2 | G20 | MONIMOD-I2C_2V5_SCL |
| | MSIO61PB2 | G21 | MONIMOD-I2C_2V5_SDA |



| | | | |
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| Document | | Designer C. Gentsos | |
| BE/CO | | Drawn by C. Gentsos | |
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DI/OT Rad-tol System Board
FPGA I/O Banks B1, B2

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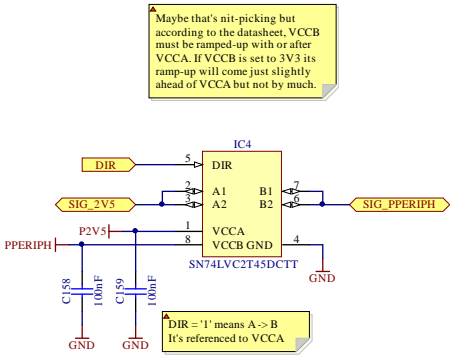
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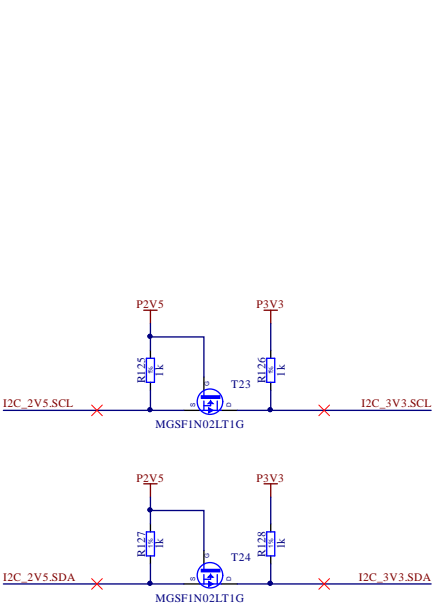
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| Document | | Designer | C. Gentsos |
| | | Drawn by | C. Gentsos |
| | | Check by | * |
| | | Last Mod. | C. Gentsos |
| | | File | Translate_3V3_I2C_to_2V5_SchDoc |
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| | | Rev | * |
| | | A3 | * |



DI/OT Rad-tol System Board

I2C Voltage Translators

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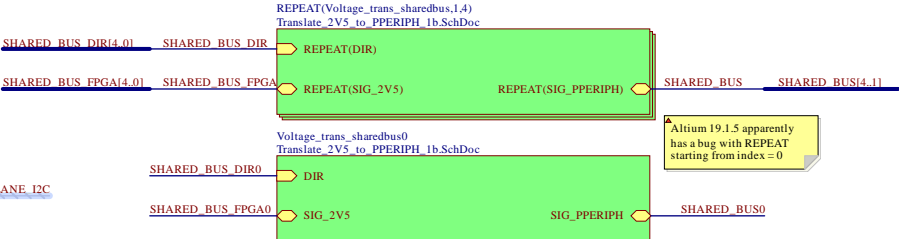
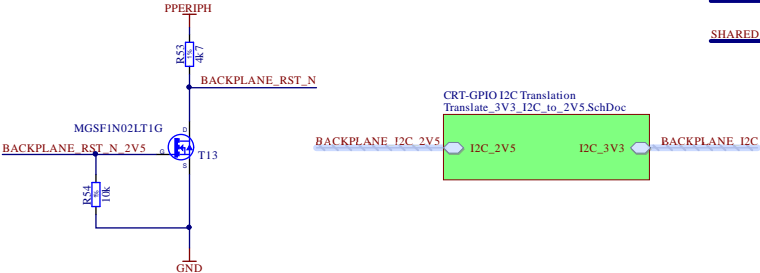
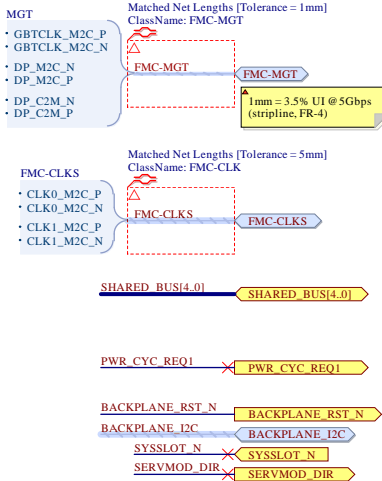
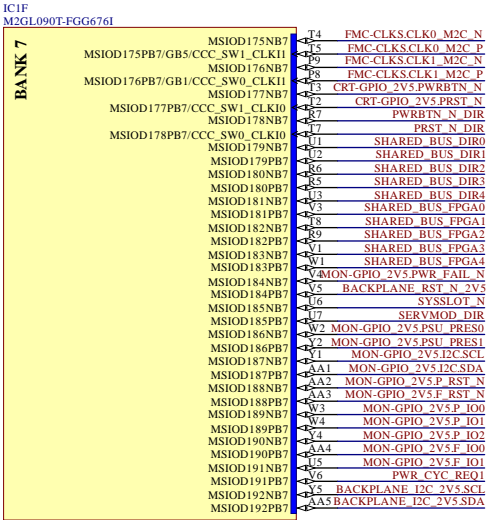
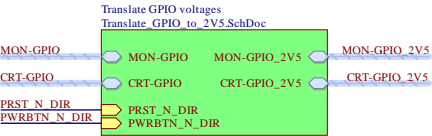
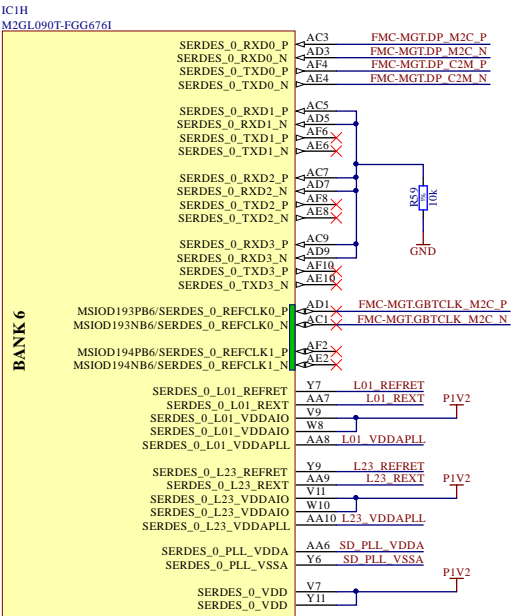
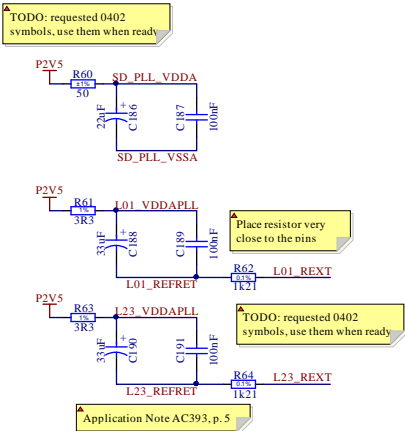
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Banks powered by 2.5V



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| BE/CO | | Drawn by | C. Gentsos |
| CERN | | Check by | * |
| | | Last Mod. | C. Gentsos |
| | | File | FPGA_Banks_6_7.SchDoc |
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| | | Size | A3 |
| | | Rev | * |
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| | | DI/OT Rad-tol System Board FPGA I/O Banks B6, B7 | |

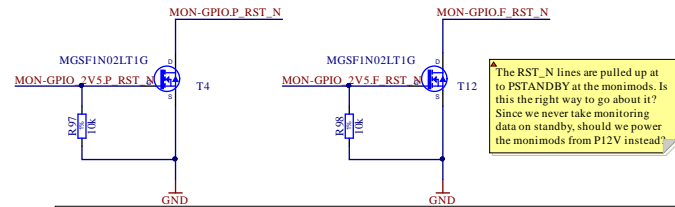
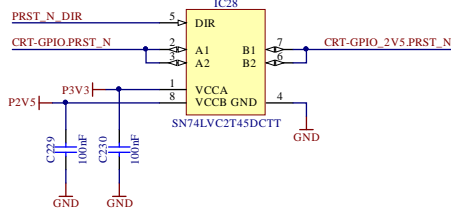
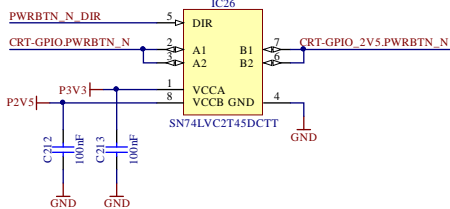
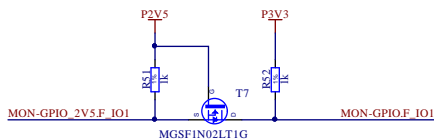
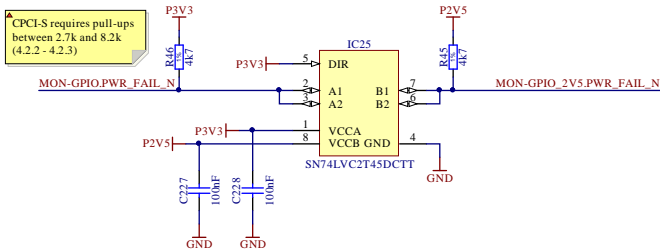
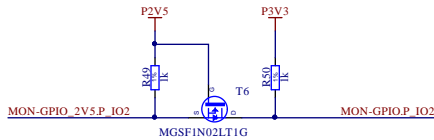
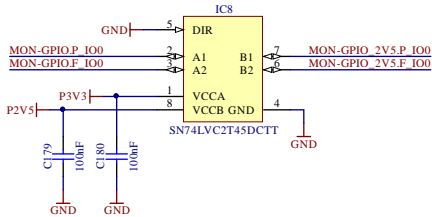
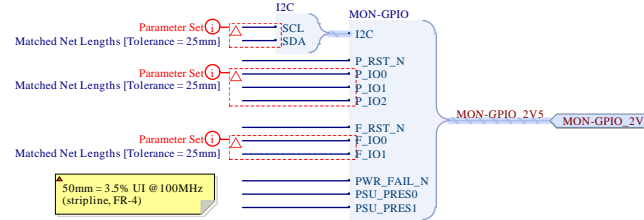
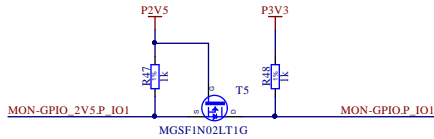
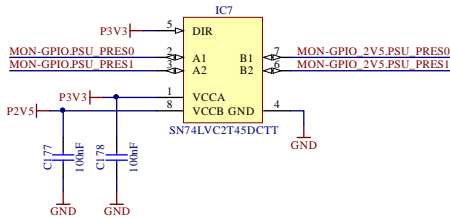
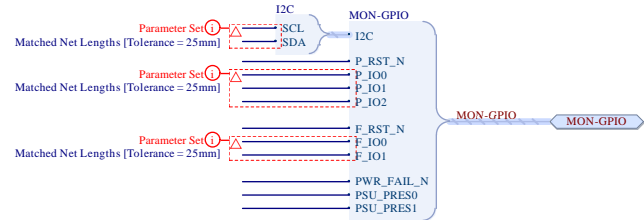
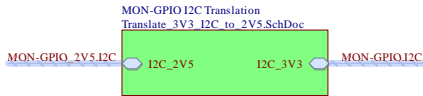
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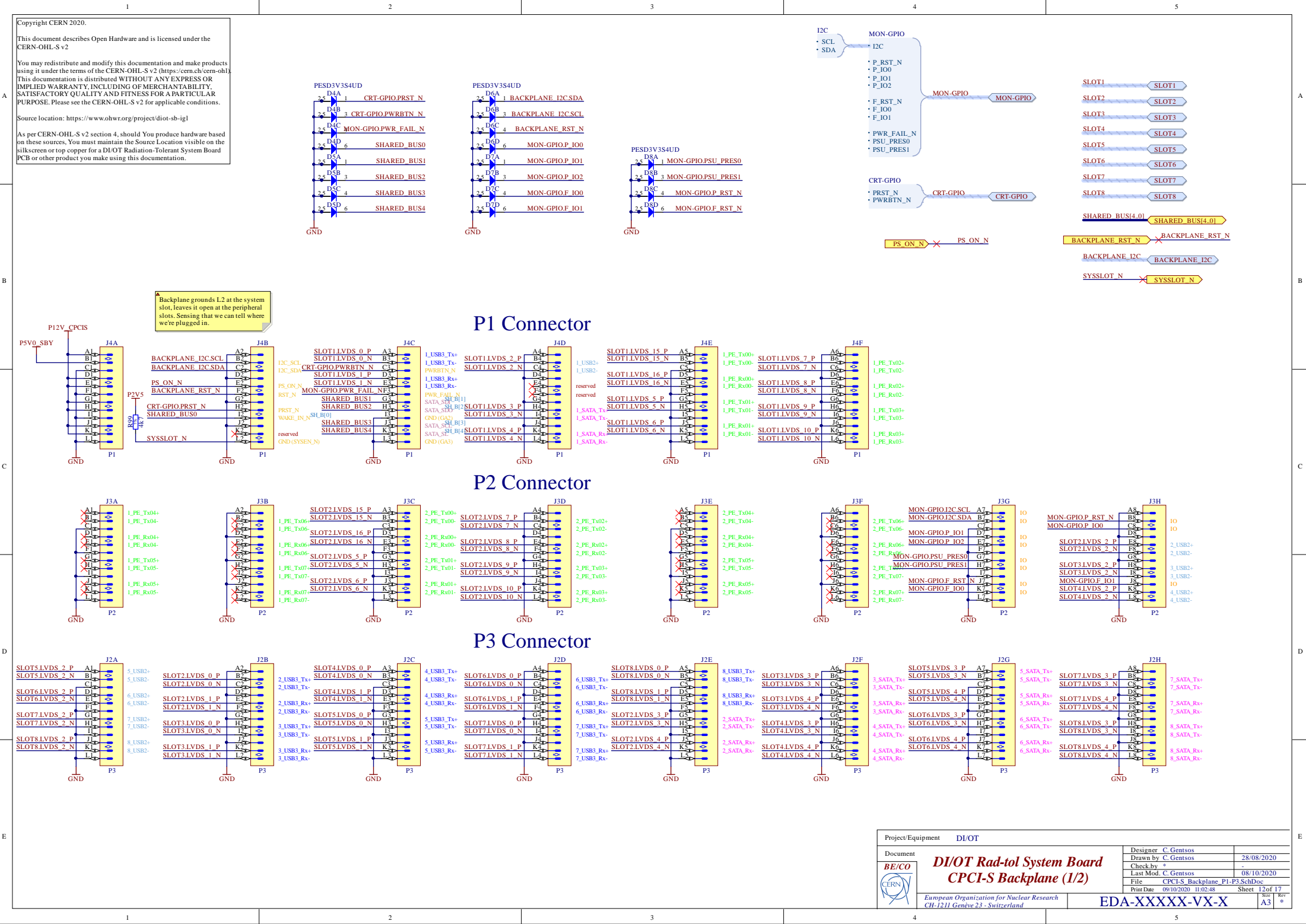
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The RST_N lines are pulled up at to PSTANDBY at the monimods. Is this the right way to go about it? Since we never take monitoring data on standby, should we power the monimods from P12V instead?

| | | | |
|--|--|-----------------------------------|--|
| Project/Equipment | | DI/OT | |
| Document | | Designer C. Gentsos | |
| BE/CO | | Drawn by C. Gentsos | |
| CERN | | Check by * | |
| DI/OT Rad-tol System Board | | Last Mod. C. Gentsos | |
| GPIO Voltage Translators | | File Translate_GPIO_to_2V5.SchDoc | |
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| EDA-XXXXX-VX-X | | A3 | |



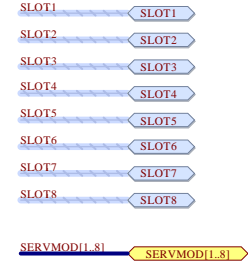
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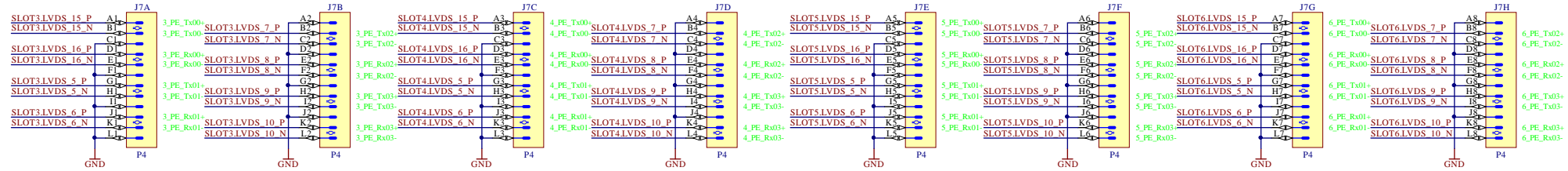
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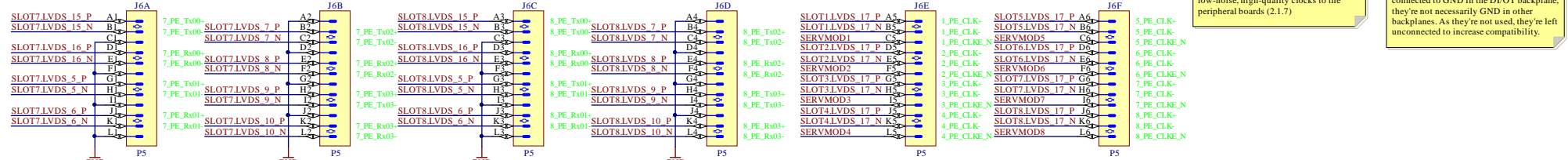
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P4 Connector



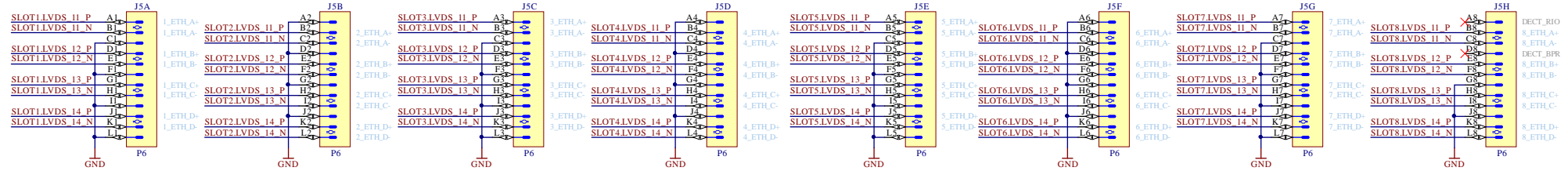
P5 Connector



1. PE_CLK diff pairs will provide low-noise, high-quality clocks to the peripheral boards (2.1.7)

The DECT_RIO and DECT_BPR pins are connected to GND in the DI/OT backplane, they're not necessarily GND in other backplanes. As they're not used, they're left unconnected to increase compatibility.

P6 Connector



| | | | |
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| Project/Equipment | | DI/OT | |
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| | | Last Mod. C. Gentsos | |
| | | File CPCL-S Backplane_P4-P6_SchDoc | |
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DI/OT Rad-tol System Board
CPCL-S Backplane (2/2)

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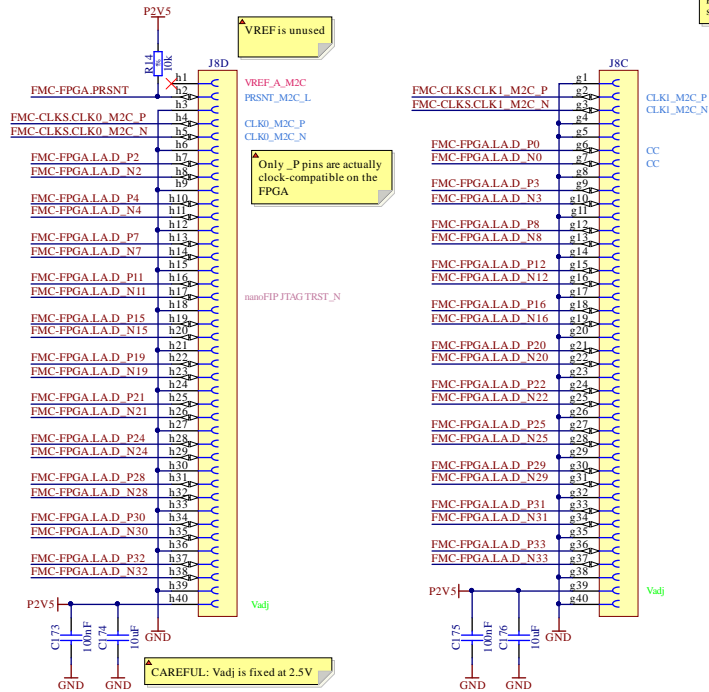
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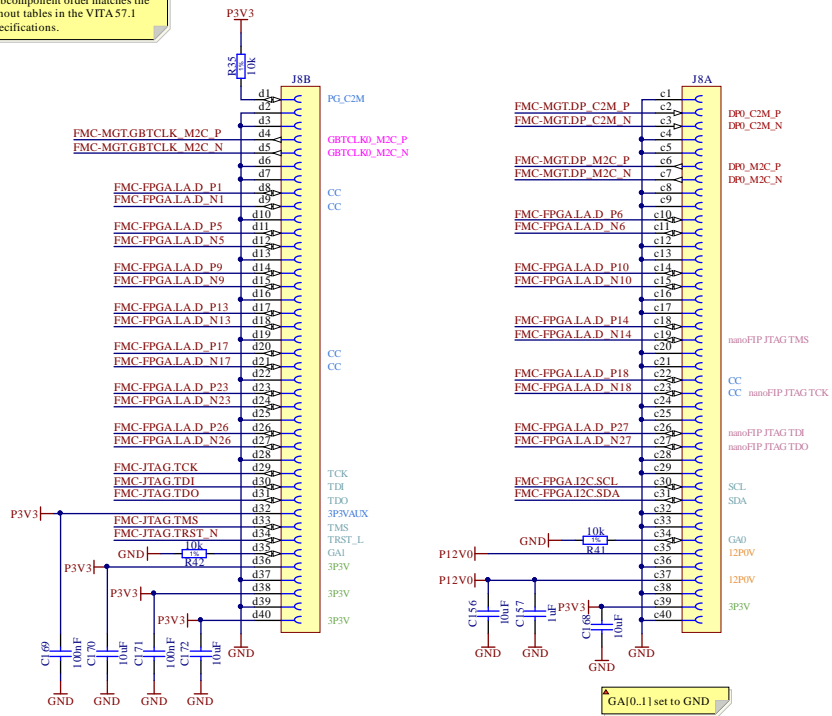
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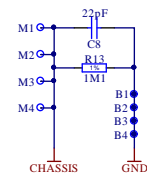
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Subcomponent order matches the pinout tables in the VITA 57.1 specifications.



Front panel and FMC slot spacers



| | | | |
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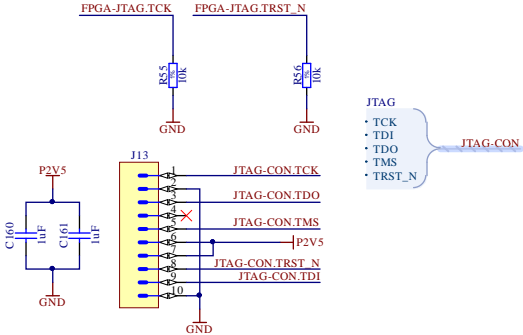
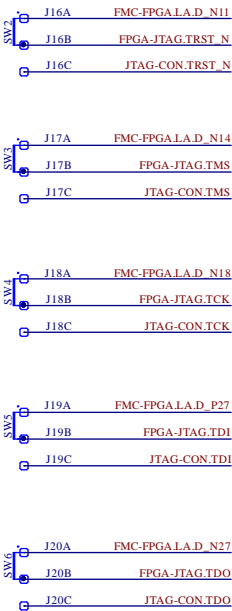
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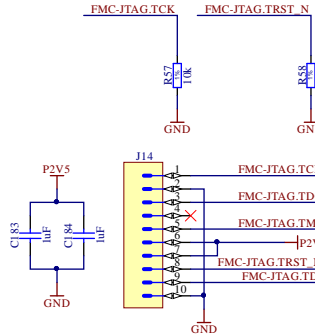
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In the Igloo2 evaluation board they use HTST-105-01-L-DV-A but there doesn't seem to be any difference.



Don't confuse this with the nanoFIP JTAG, this is just to provide an easily accessible JTAG connector to program the FMC card

| | | | |
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| | | Print Date 09/10/2020 11:02:51 | |
| | | Sheet 15 of 17 | |
| | | Size A3 | |
| | | Rev * | |

BE/CO

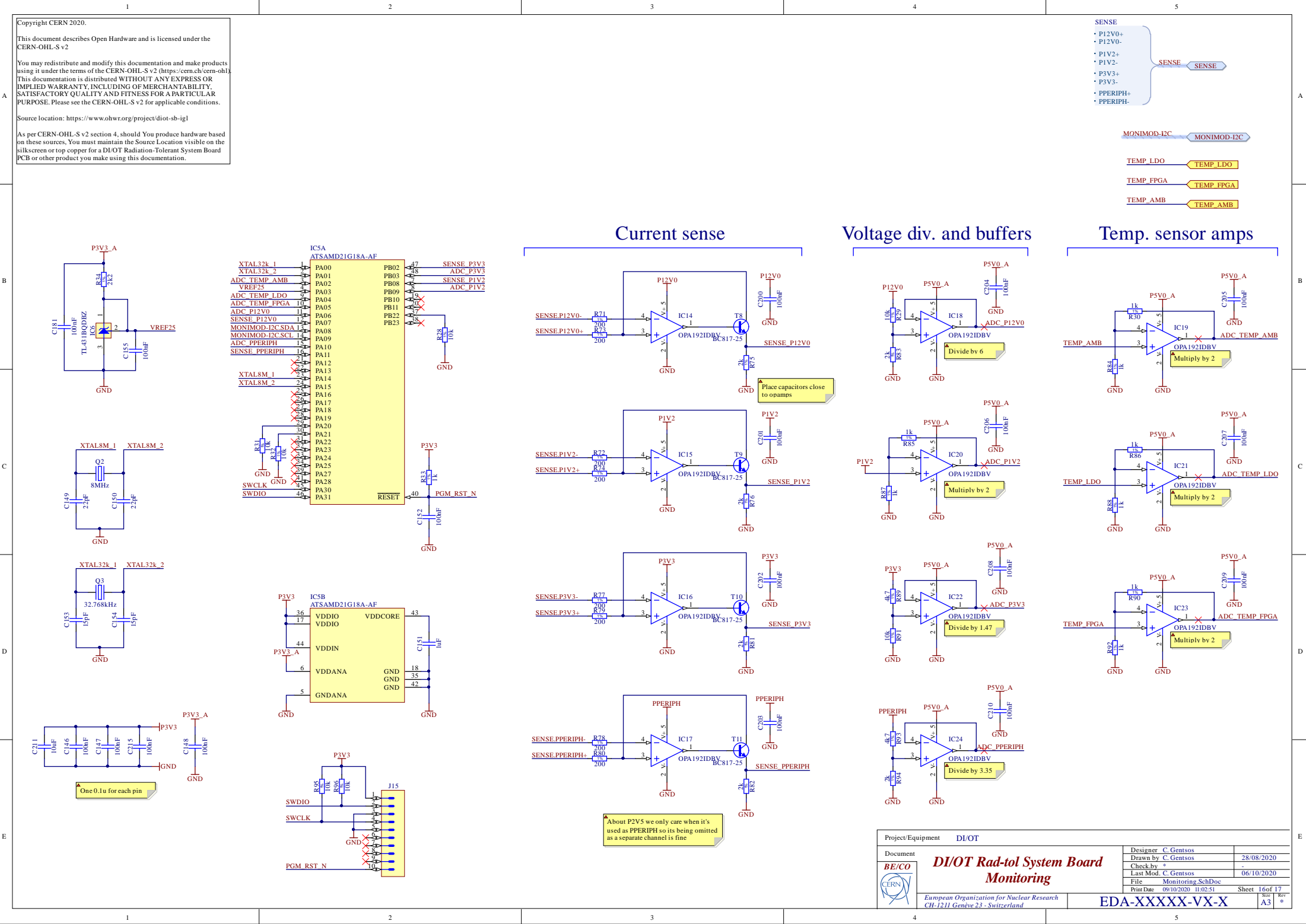
DI/OT Rad-tol System Board

JTAG Chains

European Organization for Nuclear Research

CH-1211 Genève 23 - Switzerland

EDA-XXXXX-VX-X



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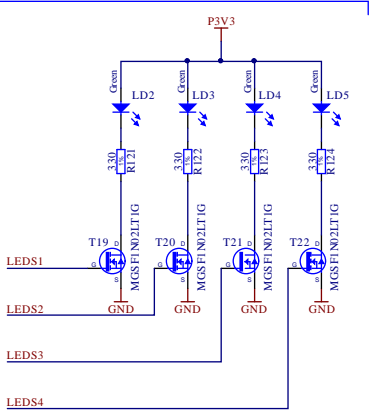
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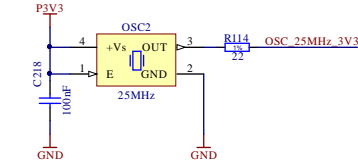
Source location: <https://www.ohwr.org/project/diot-sb-ig1>

As per CERN-OHL-S v2 section 4, should You produce hardware based on these sources, You must maintain the Source Location visible on the silkscreen or top copper for a DI/OT Radiation-Tolerant System Board PCB or other product you make using this documentation.

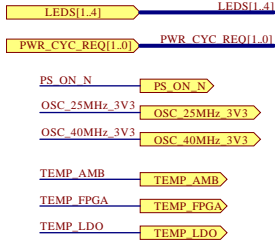
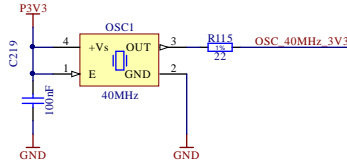
User LEDs



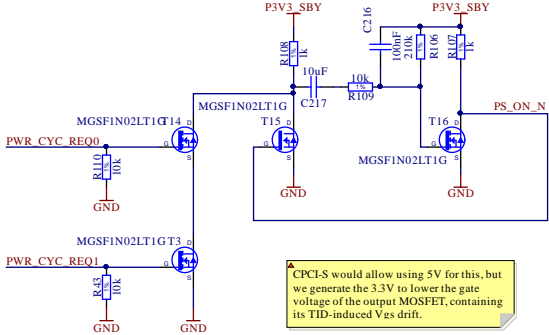
25MHz oscillator



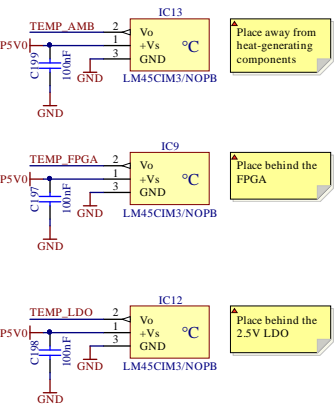
40MHz oscillator



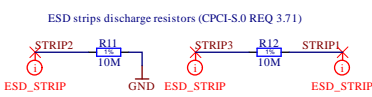
Power cycle pulse generator



Temp sensors



ESD Protection



| | | | |
|--|--|--------------------------------|--|
| Project/Equipment | | DI/OT | |
| Document | | Designer C. Gentsos | |
| BE/CO | | Drawn by C. Gentsos | |
| CERN | | Check by * | |
| DI/OT Rad-tol System Board | | Last Mod. C. Gentsos | |
| Miscellaneous | | File Top_Misc.SchDoc | |
| European Organization for Nuclear Research | | Print Date 09/10/2020 11:02:52 | |
| CH-1211 Genève 23 - Switzerland | | Sheet 17 of 17 | |
| EDA-XXXXX-VX-X | | A3 | |